T-46-19-07

PRELIMINARY





64-Macrocell Flash PLD

Features

- 64 macrocells in four logic blocks
- 32 I/O pins
- 6 dedicated inputs including 2 clock pins
- No hidden delays
- High speed
 - $-t_{PD} = 12 \text{ ns}$
 - $-t_S = 9 \text{ ns}$
 - $-t_{CO} = 9 \text{ ns}$
- Electrically alterable Flash technology
- Available in 44-pin PLCC, CLCC, and LCC packages
- Pin compatible with the CY7C371

Functional Description

The CY7C372 is a Flash Erasable Programmable Logic Device (EPLD) and is part of the FLASH370 family of high-density, high-speed PLDs. Like all members of the FLASH370 family, the CY7C372 is designed to bring the ease of use and high performance of the 22V10 to high-density PLDs.

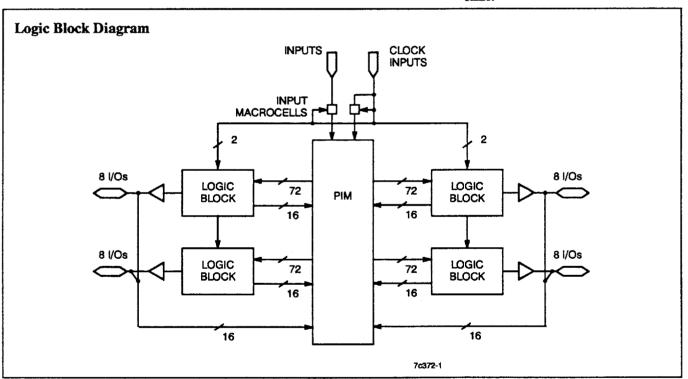
The 64 macrocells in the CY7C372 are divided between four logic blocks. Each logic block includes 16 macrocells, a 72 x 86 product term array, and an intelligent product term allocator.

The logic blocks in the FLASH370 architecture are connected with an extremely fast and predictable routing resource—the Programmable Interconnect Matrix

(PIM). The PIM brings flexibility, routability, speed, and a uniform delay to the interconnect.

Like all members of the FLASH370 family, the CY7C372 is rich in I/O resources. Every two macrocells in the device feature an associated I/O pin, resulting in 32 I/O pins on the CY7C372. In addition, there are four dedicated inputs and two input/clock pins.

Finally, the CY7C372 features a very simple timing model. Unlike other high-density PLD architectures, there are no hidden speed delays such as fanout effects, interconnect delays, or expander delays. Regardless of the number of resources used or the type of application, the timing parameters on the CY7C372 remain the same.



Selection Guide

		7C372-12	7C372-15	7C372-20
Maximum Propagation Delay tpD (ns)		12	15	20
Maximum Standby Current, I _{CC1} (mA)	Commercial	250	250	250
	Military		300	300
Maximum Operating Current, ICC2 (mA)	Commercial	280	280	280
Current, I _{CC2} (mA)	Military		330	330

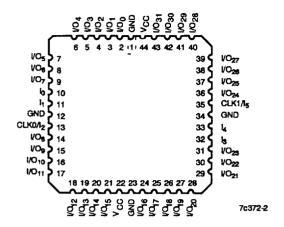
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CY7C372



Pin Configuration



Functional Description (continued)

Logic Block

The number of logic blocks distinguishes the members of the FLASH370 family. The CY7C372 includes four logic blocks. Each logic block is constructed of a product term array, a product term allocator, and 16 macrocells.

Product Term Array

The product term array in the FLASH370 logic block includes 36 inputs from the PIM and outputs 86 product terms to the product term allocator. The 36 inputs from the PIM are available in both positive and negative polarity, making the overall array size 72 x 86. This large array in each logic block allows for very complex functions to be implemented in a single pass through the device.

Product Term Allocator

The product term allocator is a dynamic, configurable resource that shifts product terms to macrocells that require them. Any number of product terms between 0 and 16 inclusive can be as-

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature 65°C to +150°C
Ambient Temperature with Power Applied 55°C to +125°C
Supply Voltage to Ground Potential 0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State 0.5V to +7.0V
DC Input Voltage 0.5V to +7.0V
DC Program Voltage

signed to any of the logic block macrocells (this is called product term steering). Furthermore, product terms can be shared among multiple macrocells. This means that product terms that are common to more than one output can be implemented in a single product term. Product term steering and product term sharing help to increase the effective density of the FLASH370 PLDs. Note that product term allocation is handled by software and is invisible to the user.

I/O Macrocell

Half of the macrocells on the CY7C372 have separate I/O pins associated with them. In other words, each I/O pin is shared by two macrocells. The input to the macrocell is the sum of between 0 and 16 product terms from the product term allocator. The macrocell includes a register that can be optionally bypassed. It also has polarity control, and two global clocks to trigger the register. The I/O macrocell also features a separate feedback path to the PIM so that the register can be buried if the I/O pin is used as an input.

Buried Macrocell

The buried macrocell is very similar to the I/O macrocell. Again, it includes a register that can be configured as combinatorial, as a D flip-flop, a T flip-flop, or a latch. The clock for this register has the same options as described for the I/O macrocell. One difference on the buried macrocell is the addition of input register capability. The user can program the buried macrocell to act as an input register whose input comes from the I/O pin associated with the neighboring macrocell. The output of all buried macrocells is sent directly to the PIM regardless of its configuration.

Programmable Interconnect Matrix

The Programmable Interconnect Matrix (PIM) connects the four logic blocks on the CY7C372 to the inputs and to each other. All inputs (including feedbacks) travel through the PIM. There is no speed penalty incurred by signals traversing the PIM.

Development Tools

Development software for the CY7C372 is available from Cypress's Warp2 and Warp3 software packages. Both of these products are based on the IEEE standard VHDL language. Cypress also supports third-party vendors such as ABEL, CUPL, and LOG/iC. Please contact your local Cypress representative for further information.

Output Current into Outputs	16 mA
Static Discharge Voltage (per MIL-STD-883, Method 3015)	>2001V
Latch-Up Current	>200 mA

Operating Range

Range	Ambient Temperature	V _{CC}
Commercial	0°C to +70°C	5V ± 5%
Military ^[1]	– 55°C to +125°C	5V ± 10%



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Electrical Characteristics Over the Operating Range^[2]

		Test Conditions		7C:	372		
Parameter	Description			Min.	Max.	Unit	
V _{OH}	Output HIGH Voltage $V_{CC} = Min.$ $I_{OH} = -3.2 \text{ mA (Com'l/Ind)}$		2.4		V		
			$I_{OL} = -2.0 \text{ mA (Mil)}$				V
V _{OL}	Output LOW Voltage	V _{CC} = Min.	$I_{OH} = 16 \text{ mA (Com'l/I}$	nd)		0.5	V
			$I_{OL} = 12 \text{ mA (Mil)}$		•		V
V _{IH}	Input HIGH Voltage			2.0	7.0	V	
V _{IL}	Input LOW Voltage				-0.5	0.8	V
I _{IX}	Input Load Current	$GND \leq V_{I} \leq V_{CC}$		-10	+10	μА	
I _{OZ}	Output Leakage Current	GND \leq V _O \leq V _{CC} , Output Disabled		-50	+50	μА	
Ios	Output Short Circuit Current ^[3]	$V_{CC} = Max., V_{OUT} = 0.5V$		-30	90	mA	
I _{CC1}	Power Supply Current	$ \begin{aligned} &V_{CC} = \text{Max., } I_{OUT} = 0 \text{ mA,} \\ &f = 0 \text{ mHz, } V_{IN} = \text{GND, } V_{CC} \end{aligned} \qquad \qquad \begin{aligned} &\text{Com'l} \\ &\text{Mil} \end{aligned} $		•	250	mA	
	(Standby)				300	1	
I _{CC2}	Power Supply Current	$V_I = V_{CC}$ or GND, $f = 40$ MHz Com'l		Com'l		280	mA
				Mil	V. i.i	330	

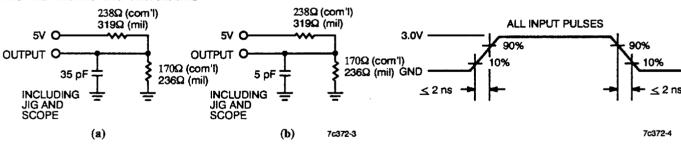
Capacitance^[4]

Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	$V_{IN} = 2.0V$ at $f=1$ MHz	10	pF
C _{OUT}	Output Capacitance	$V_{OUT} = 2.0V$ at $f = 1$ MHz	12	pF

Notes:

- 1. TA is the "instant on" case temperature.
- See the last page of this specification for Group A subgroup testing information.
- Not more than one output should be tested at a time. Duration of the short circuit should not exceed 1 second. V_{OUT} = 0.5V has been chosen to avoid test problems caused by tester ground degradation.
- Tested initially and after any design or process changes that may affect these parameters.

AC Test Loads and Waveforms

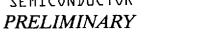


Equivalent to: THÉVENIN EQUIVALENT 99 Ω (com'l) 136 Ω (mil) 2.08V (com'l) 0UTPUT 0 2.13V (mil)

Revision: Monday, January 4, 1993

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		7C37	2-12	7C37	2-15	7C372-20		1	
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Unit	
Combinato	rial Mode Parameters						•		
t _{PD}	Input to Combinatorial Output		12		15		20	ns	
t _{PDL}	Input to Output Through Transparent Input or Output Latch		14		17		22	ns	
tPDLL	Input to Output Through Transparent Input and Output Latches		16		19		24	ns	
t _{EA}	Input to Output Enable		16		19		24	ns	
ter	Input to Output Disable		16		19		24	ns	
Input Regi	stered/Latched Mode Parameters								
$t_{ m WL}$	Clock or Latch Enable Input LOW Time	5		6		8		ns	
t _{WH}	Clock or Latch Enable Input HIGH Time	5		6		8		ns	
t _{IS}	Input Register or Latch Set-Up Time	2		3		4		ns	
t _{IH}	Input Register or Latch Hold Time	2		3		4		ns	
t _{ICO}	Input Register Clock or Latch Enable to Combinatorial Output		16		19		24	ns	
tICOL	Input Register Clock or Latch Enable to Output Through Transparent Output Latch		18		21		26	ns	
f _{MAX1}	Maximum Frequency of (2) CY7C372s in Input Registered Mode (Lesser of 1/(t _{ICO} + t _{IS}) and 1/(t _{WL} + t _{WH}))	55.5		45.5		35.7		МН	
f _{MAX2}	Maximum Frequency Data Path in Input Registered/Latched Mode (Least of 1/t _{ICO} , 1/(t _{WL} + t _{WH}), 1/(t _{IS} + t _{IH}))	62.5		52.6		41.7		MH	
Output Re	gistered/Latched Mode Parameters			<u> </u>		*	<u> </u>		
tco	Clock or Latch Enable to Output		- 9		12		15	ns	
t _S	Set-Up Time from Input to Clock or Latch Enable	9		12		15		ns	
t _H	Register or Latch Data Hold Time	0		0		0		ns	
t _{CO2}	Output Clock or Latch Enable to Output Delay (Through Memory Array)		16		19		24	ns	
tscs	Output Clock or Latch Enable to Output Clock or Latch Enable (Through Memory Array)	12		15		20		ns	
t _{SL}	Set-Up Time from Input Through Transparent Latch to Output Register Clock or Latch Enable	12		15		20		ns	
t _{HL}	Hold Time for Input Through Transparent Latch from Output Register Clock or Latch Enable	0		0		0		ns	
f _{MAX3}	Maximum Frequency of (2) CY7C372s in Output Registered Mode (Lesser of 1/(t _{CO} + t _S) and 1/(t _{WL} + t _{WH}))	55.5		41.7		33.3		MH	
f _{MAX4}	Maximum Frequency Data Path in Output Registered/Latched Mode (Lesser of 1/(t _{WL} + t _{WH}), 1/(t _S + t _H), or 1/t _{CO})	100		83.3		62.5		MH	
f _{MAXS}	Maximum Frequency with Internal Feedback in Output Registered Mode (Least of $1/t_S$, $1/(t_S + t_H)$, or $1/t_{CO}$) ^[4]	83.3		66.6		50		МН	
Pipelined I	Mode Parameters								
t _{ICS}	Input Register Clock to Output Register Clock	12		15		20		ns	
f _{MAX6}	Maximum Frequency in Pipelined Mode (Least of $1/(t_{CO} + t_{IS})$, $1/t_{ICS}$, $1/(t_{WL} + t_{WH})$, $1/(t_{IS} + t_{IH})$, or $1/t_{SCS}$)	83.3		66.6		50.0		MH	

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Note:
5. All AC parameters are measured with 16 outputs switching.



CY7C372



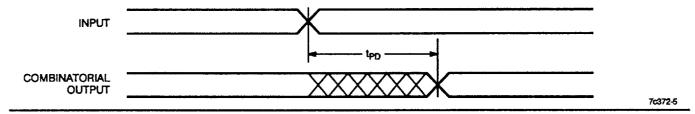
Switching Characteristics Over the Operating Range^[5] (continued)

		7C371=12	7C371-15		7C371-20		
Parameter	Description	Min. Max.	Min.	Max.	Min. Max.		Unit
Reset/Pres	et Parameters			1	<u> </u>	1	
t _{RW}	Asynchronous Reset Width	12	15		20		ns
t _{RR}	Asynchronous Reset Recovery Time	14	17		22		ns
t _{RO}	Asynchronous Reset to Output	18		21		26	ns
t _{PW}	Asynchronous Preset Width	12	15		20		ns
tpR	Asynchronous Preset Recovery Time	14	17		22		ns
t _{PO}	Asynchronous Preset to Output	18		21		26	ns

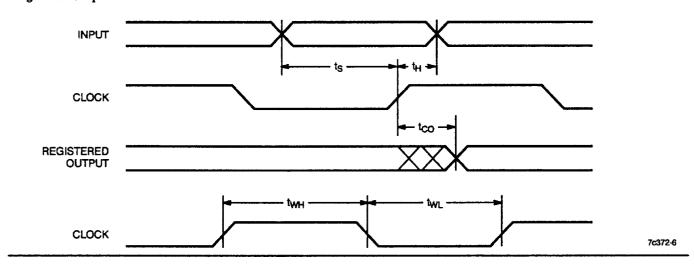
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Switching Waveforms

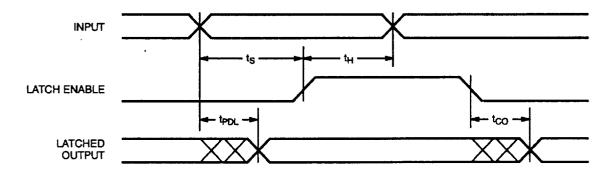
Combinatorial Output



Registered Output



Latched Output



7c372-7

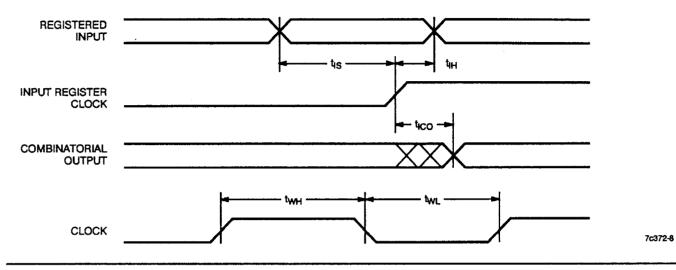
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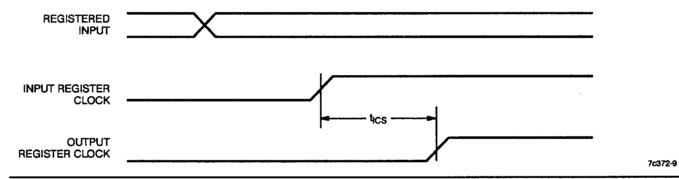
7c372-10

Switching Waveforms (continued)

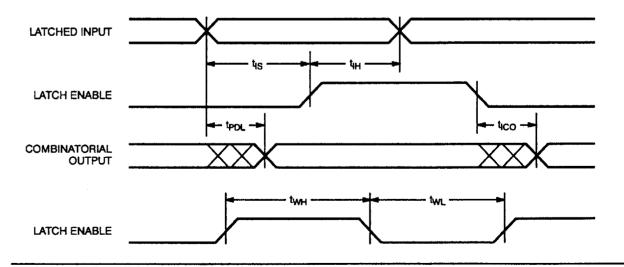
Registered Input



Input Clock to Output Clock



Latched Input



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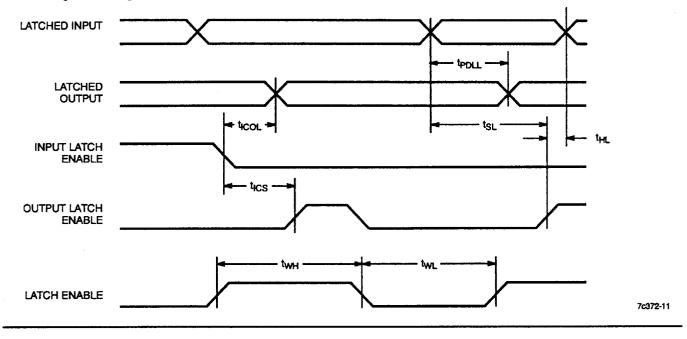
CY7C372

7c372-13

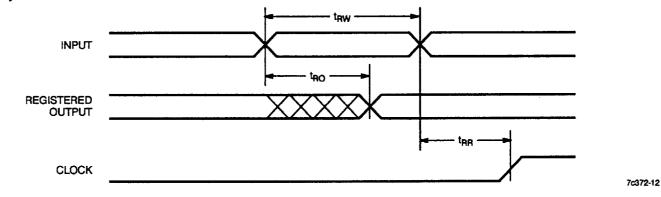


Switching Waveforms (continued)

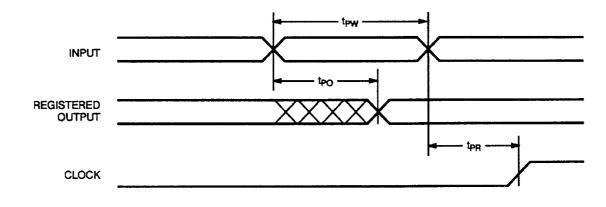
Latched Input and Output



Asynchronous Reset



Asynchronous Preset



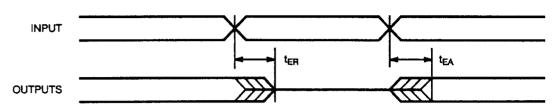
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CY7C372



Switching Waveforms (continued)

Output Enable/Disable



7c372-14

Ordering Information

Speed (ns)	Ordering Code	Package Type	Operating Range
12	CY7C372-12JC	J67	Commercial
15	CY7C372-15JC	J67	Commercial
	CY7C372-15LM	1.67	Military
20	CY7C372-20JC	J67	Commercial
	CY7C372-20LM	L67	Military

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MILITARY SPECIFICATIONS Group A Subgroup Testing DC Characteristics

Parameter	Subgroups
V _{OH}	1, 2, 3
V _{OL}	1, 2, 3
V _{IH}	1, 2, 3
V_{IL}	1, 2, 3
I _{IX}	1, 2, 3
I _{OZ}	1, 2, 3
I _{CC1}	1, 2, 3
I _{CC2}	1, 2, 3

Switching Characteristics

Parameter	Subgroups
t _{PD}	7, 8, 9, 10, 11
t _{PDL}	7, 8, 9, 10, 11
tPDLL	7, 8, 9, 10, 11
tco	7, 8, 9, 10, 11
t _{ICO}	7, 8, 9, 10, 11
ticol	7, 8, 9, 10, 11
t _S	7, 8, 9, 10, 11
t _{SL}	7, 8, 9, 10, 11
t _H	7, 8, 9, 10, 11
t _{HL}	7, 8, 9, 10, 11
t _{IS}	7, 8, 9, 10, 11
t _{IH}	7, 8, 9, 10, 11
t _{ICS}	7, 8, 9, 10, 11
t _{EA}	7, 8, 9, 10, 11
t _{ER}	7, 8, 9, 10, 11

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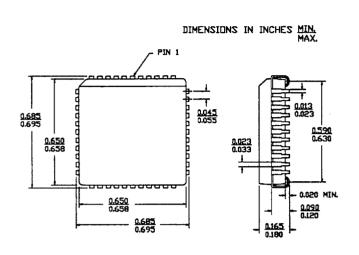






Package Diagrams

44-Lead Plastic Leaded Chip Carrier J67



44-Square Leadless Chip Carrier L67 MIL-STD-1835 C-5

